

ATMXT1664TD-C2UEN 2.0

maXTouch 1664-node Touchscreen Controller Product Brief

Description

The ATMXT1664TD-C2UEN 2.0 uses a unique charge-transfer acquisition engine to implement Microchip's patented capacitive sensing method. Coupled with a state-of-the-art CPU, the entire touchscreen sensing solution can measure, classify and track a number of individual finger touches with a high degree of accuracy in the shortest response time. The ATMXT1664TD-C2UEN 2.0 allows for both mutual and self capacitance measurements, with the self capacitance measurements being used to augment the mutual capacitance measurements to produce reliable touch information.

maXTouch[®] Adaptive Sensing Technology

- Up to 41 X (transmit) lines and 71 Y (receive) lines for use by a touchscreen and/or key array
- A maximum of 1664 nodes can be allocated to the touch sensor
- Touchscreen size of 15.62 inches (16:10 aspect ratio), assuming a sensor electrode pitch of 6.5 mm. Other sizes are possible with different electrode pitches and appropriate sensor material
- Multiple touch support with up to 16 concurrent touches tracked in real time
- HID Mouse mode reporting of single touches to the host, subject to configuration

Touch Sensor Technology

- On-cell/touch-on display support including OLED and LCD
- Discrete/out-cell support including glass and PET filmbased sensors
- · Synchronization with display refresh timing capability
- Support for standard (for example, Diamond) and proprietary sensor patterns (review of designs by Microchip or a Microchip-qualified touch sensor module partner is recommended)

Front Panel Material and Design

- Works with PET or glass, including curved profiles (configuration and stack-up to be approved by Microchip or a Microchip-qualified touch sensor module partner)
- 10 mm glass (or 5 mm PMMA) with bare finger (dependent on sensor size, touch size, configuration and stack-up)
- 6 mm glass (or 3 mm PMMA) with multi-finger 5 mm glove (2.7 mm PMMA equivalent) (dependent on sensor size, touch size, configuration and stack-up)
- Support for non-rectangular sensor designs (for example, circular, rounded or with cutouts)

Touch Performance

- Moisture/Water Compensation
 - No false touch with condensation or water drop up to 22 mm diameter
 - One-finger tracking with condensation or water drop up to 22 mm diameter
- Multiple acquisition schemes for robust and sensitive multi-touch sensing, including:
 - Mutual capacitance capacitance measurements
 - Self Capacitance measurements
 - P2P Mutual Capacitance measurements
- Noise suppression technology to combat ambient and power-line noise
 - Up to 240 V_{PP} between 1 Hz and 1 kHz sinusoidal waveform (no touches)
 - Up to 20 V_{PP} between 1 kHz and 1 MHz sinusoidal waveform
- Stylus Support
 - Supports passive stylus with 1.5 mm contact diameter, subject to configuration, stack-up, and sensor design
- Burst Frequency
 - Flexible and dynamic Tx burst frequency selection to reduce EMC disturbance
 - Configurable Tx waveform shaping to reduce emissions
- Scan Speed
 - Typical report rate for 10 touches ≥110 Hz (subject to configuration)
 - Initial touch latency <20 ms for first touch from idle (subject to configuration)
 - Configurable for power and speed optimization

- Touch panel failure detection
 - Automatic touch sensor diagnostics during run time to support the implementation of safety critical features
 - Diagnostics reported using dedicated output pin or by standard Object Protocol messages
 - Configurable test limits

Keys

- Up to 32 nodes can be allocated as mutual capacitance sensor keys in addition to the touchscreen, defined as 1 key array (subject to availability of X and Y lines and other configurations)
- · Adjacent Key Suppression (AKS) technology is supported for false key touch prevention

PWM Signal Generation

· PWM Output for display backlight control, audible speaker/buzzer output, or simple haptic feedback

Enhanced Algorithms

- · Lens bending algorithms to remove display noise
- · Touch suppression algorithms to remove unintentional large touches
- · Palm Recovery Algorithm for quick restoration to normal state
- · Enhanced Touch Separation algorithm for improved two touch separation/tracking in all directions.

On-chip Gestures

· Reports one-touch and two-touch gestures

Data Store

- 60-byte CRC checksummed data area for use as a run-time Product Data Store Area
- 64-byte data area for user's custom data (not CRC checksummed)

Device Security

- Encrypted configuration parameters and touch coordinate reports (OBP messages) using customer's own security key
- · Firmware Authentication mechanism to ensure the authenticity of the application firmware in the device

Power Saving

- · Programmable timeout for automatic transition from Active to Idle state
- · Pipelined analog sensing detection and digital processing to optimize system power efficiency

Application Interfaces

- Client interface for main communication with the device. Can be one of:
 - I²C interface, with support for Standard mode (up to 100 kHz), Fast mode (up to 400 kHz), Fast-mode Plus (up to 1 MHz), High Speed mode (up to 3.4 MHz)
 - HID-I²C interface for Microsoft Windows 10
 - USB HID interface for Microsoft Windows 10
- · Interrupt to indicate when a message is available
- · Additional SPI Debug Interface to read the raw data for tuning and debugging purposes

Power Supply

- Digital (Vdd) 3.3V nominal
- Digital I/O (VddIO) 1.8V to 3.3V (I²C mode), 3.3V nominal (USB mode)
- Analog (AVdd) 3.3V nominal
- High voltage external X line drive (XVdd) up to 9.2V

Package

• 162-ball UFBGA 10 × 5 × 0.6 mm, 0.5 mm pitch

Operating Temperature

• −40°C to +85°C

Design Services

• Specific design and tuning tools available as maXTouch Studio plug-ins

ATMXT1664TD-C2UEN 2.0

PIN CONFIGURATION

162-ball UFBGA

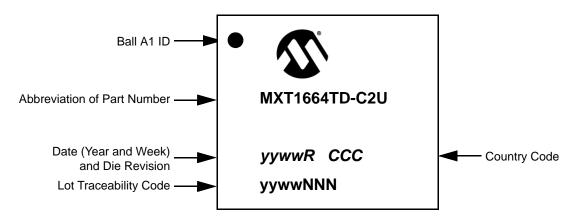
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DS40002578A-page 4

1.0 PACKAGING INFORMATION

1.1 Package Marking Information

1.1.1 162-BALL UFBGA



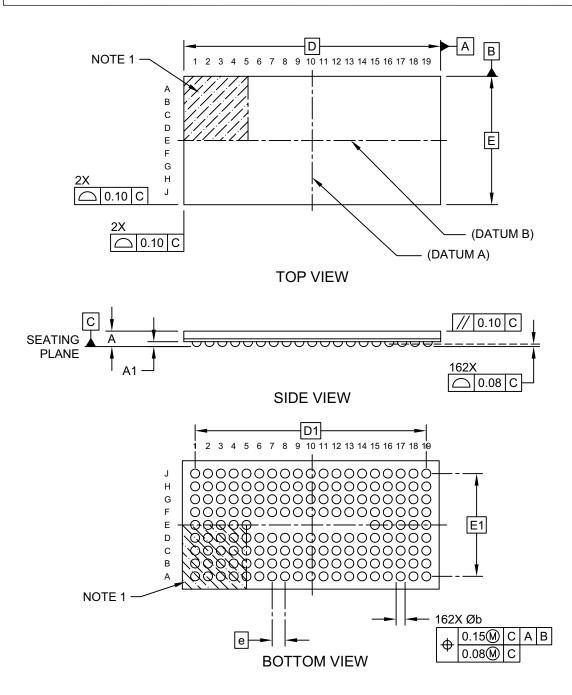
1.1.2 ORDERABLE PART NUMBERS

The product identification system for maXTouch devices is described in "Product Identification System" on page 10. That section also lists example part numbers for the device.

1.2 Package Details

162-Ball Ultra Thin Fine Pitch Ball Grid Array (C6B) - 10x5x0.6 mm Body [UFBGA] Atmel Legacy Global Package Code CAK

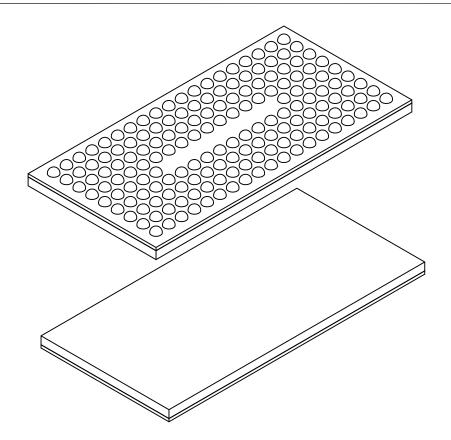
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-21167 Rev A Sheet 1 of 2

162-Ball Ultra Thin Fine Pitch Ball Grid Array (C6B) - 10x5x0.6 mm Body [UFBGA] Atmel Legacy Global Package Code CAK

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



		Units	MILLIMETERS			
	Dimension	Limits	MIN	NOM	MAX	
Number of Terminals		Ν		162		
Pitch		е		0.50 BSC		
Overall Height		Α	0.488	0.546	0.60	
Standoff		A1	0.120	0.155	0.190	
Overall Length		D		10.00 BSC		
Overall Ball Spacing		D1		9.00 BSC		
Overall Width		Е		5.00 BSC		
Exposed Pad Width		E1		4.00 BSC		
Ball Diameter		b	0.20	0.25	0.30	

Notes:

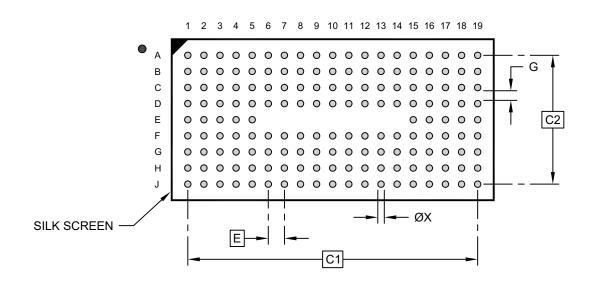
- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-21167 Rev A Sheet 2 of 2

162-Ball Ultra Thin Fine Pitch Ball Grid Array (C6B) - 10x5x0.6 mm Body [UFBGA] Atmel Legacy Global Package Code CAK

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS			
Dimension	Limits	MIN	NOM	MAX	
Contact Pitch	ш		0.50 BSC		
Contact Pad Spacing	C1		9.00 BSC		
Contact Pad Spacing	C2		4.00 BSC		
Contact Pad Diameter (X162)	X1			0.20	
Contact Pad to Contact Pad	G	0.30			

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-23167 Rev A

APPENDIX A: REVISION HISTORY

Revision A (April 2024)

Initial edition for firmware revision 2.0.AA - Release

PRODUCT IDENTIFICATION SYSTEM

The table below gives details on the product identification system for maXTouch devices. See "Orderable Part Numbers" below for example part numbers for the mXT1664TD-C2UEN.

To order or obtain information, for example on pricing or delivery, refer to the factory or the listed sales office.

 Device	 Package	e Te	 emperature Range	ا Tape and Reel Option	 Pattern
Device:	Base dev	ice nam	ne		
Package:	C2	=	UFBGA (U	Itra Thin Fine-pit	ch Ball Grid Array)
	NH	=	UFBGA (U	Itra Thin Fine-pit	ch Ball Grid Array)
	C4	=	X1FBGA (Extra Thin Fine-p	oitch Ball Grid Array)
	MA	=	XQFN (Su	per Thin Quad F	lat No Lead Sawn)
	MA5	=	XQFN (Su	per Thin Quad F	lat No Lead Sawn)
Temperature Range:	U	=	–40°C to +	85°C (Grade 3)	
Tape and Reel Option: (1)	Blank	=	Standard I	Packaging (Tube	or Tray)
	R	=	Tape and I	Reel	
Pattern:	Extensior (Blank Ot			or Special Requ	irements
Note 1: Tape and Reel identii	,		,		otion. This identifier is used for

Orderable Part Numbers

Orderable Part Number	Firmware Revision	Family ID	Variant ID	Description
ATMXT1664TD-C2UEN1 (Supplied in trays)	20.44	0xA4		162-ball UFBGA 10 × 5 × 0.6 mm, RoHS compliant
ATMXT1664TD-C2UREN1 (Supplied in tape and reel)	2.0.AA	UXA4	0x5C	Industrial grade; not suitable for automotive characterization

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